

Product Change Notification PCN95007

Qualification of Integrated Packaging Assembly Corporation

Subject: Qualification of Integrated Packaging Assembly Corporation (IPAC) as a New Assembly Subcontractor.

Products Affected: Plastic Quad Flat Packs (TQ, PQ).

Change Description: The addition of IPAC in San Jose, CA, as a Qualified Assembly Facility. IPAC will start production of Plastic Quad Flat Pack products for Xilinx in March, 1996 after successfully completing qualification testing.

Product Change: There are no changes in electrical or mechanical specifications. The package piece parts (mold compound, leadframe, etc.) as well as the manufacturing processes are totally compatible with Plastic Quad Flat Pack products that Xilinx currently supplies from other assembly facilities.

Reason For Change: To provide additional assembly capacity for Xilinx Plastic Quad Flat Pack products. This change is part of our continuous effort towards improving total customer satisfaction.

Qualification Data: Xilinx has performed an on-site audit of this facility in April, 1995, to verify IPAC's conformance to Xilinx' and ISO-9002 quality system requirements. Reliability Qualification Testing is in progress. Summary qualification test will be made available upon completion of all required testing.

Traceability: For traceability purposes, the back (bottom) side marking will show a "L" prefix on the assembly lot code.

Immediate response to this notification is not required. For any questions regarding this PCN you may contact Xilinx via email at "pcn@xilinx.com" or by FAX at (408) 559-1368.